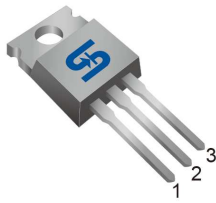


### TO-220



### Pin Definition:

1. Gate
2. Drain
3. Source

### PRODUCT SUMMARY

| $V_{DS}$ (V) | $R_{DS(on)}$ (m $\Omega$ ) | $I_D$ (A) |
|--------------|----------------------------|-----------|
| 60           | 6.7 @ $V_{GS}=10V$         | 100       |

### Features

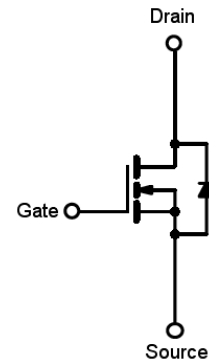
- Advanced Trench Technology
- Low  $R_{DS(on)}$  6.7m $\Omega$  (Max.)
- Low gate charge typical @ 81nC (Typ.)
- Low  $C_{rss}$  typical @ 339pF (Typ.)

### Ordering Information

| Part No.        | Package | Packing      |
|-----------------|---------|--------------|
| TSM100N06CZ C0G | TO-220  | 50pcs / Tube |

Note: "G" denote for Halogen Free Product

### Block Diagram



N-Channel MOSFET

### Absolute Maximum Rating ( $T_a = 25^\circ\text{C}$ unless otherwise noted)

| Parameter                            | Symbol           | Limit                                        | Unit             |
|--------------------------------------|------------------|----------------------------------------------|------------------|
| Drain-Source Voltage                 | $V_{DS}$         | 60                                           | V                |
| Gate-Source Voltage                  | $V_{GS}$         | $\pm 20$                                     | V                |
| Continuous Drain Current             | $I_D$            | $T_C=25^\circ\text{C}$<br>100 <sup>(3)</sup> | A                |
|                                      |                  | $T_C=70^\circ\text{C}$<br>80                 |                  |
|                                      |                  | $T_A=25^\circ\text{C}$<br>14                 |                  |
|                                      |                  | $T_A=70^\circ\text{C}$<br>11                 |                  |
| Drain Current-Pulsed Note 1          | $I_{DM}$         | 400                                          | A                |
| Avalanche Current, L=0.1mH           | $I_{AS}$         | 71                                           | A                |
| Avalanche Energy, L=0.1mH            | $E_{AS}, E_{AR}$ | 400                                          | mJ               |
| Maximum Power Dissipation            | $P_D$            | $T_C=25^\circ\text{C}$<br>167                | W                |
|                                      |                  | $T_C=70^\circ\text{C}$<br>107                |                  |
|                                      |                  | $T_A=25^\circ\text{C}$<br>2                  |                  |
|                                      |                  | $T_A=70^\circ\text{C}$<br>1.3                |                  |
| Storage Temperature Range            | $T_{STG}$        | -55 to +150                                  | $^\circ\text{C}$ |
| Operating Junction Temperature Range | $T_J$            | -55 to +150                                  | $^\circ\text{C}$ |

\* Limited by maximum junction temperature

### Thermal Performance

| Parameter                                | Symbol         | Limit | Unit               |
|------------------------------------------|----------------|-------|--------------------|
| Thermal Resistance - Junction to Case    | $R\theta_{JC}$ | 0.8   | $^\circ\text{C/W}$ |
| Thermal Resistance - Junction to Ambient | $R\theta_{JA}$ | 62.5  | $^\circ\text{C/W}$ |

Notes: Surface mounted on FR4 board  $t \leq 10\text{sec}$

**Electrical Specifications** (Ta = 25°C unless otherwise noted)

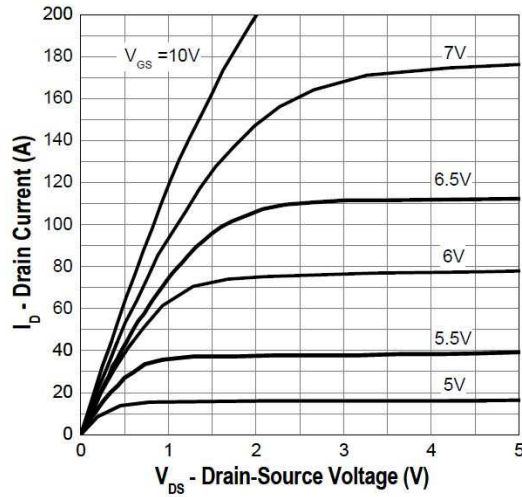
| Parameter                                             | Conditions                                         | Symbol       | Min | Typ  | Max  | Unit |
|-------------------------------------------------------|----------------------------------------------------|--------------|-----|------|------|------|
| Static                                                |                                                    |              |     |      |      |      |
| Drain-Source Breakdown Voltage                        | $V_{GS} = 0V, I_D = 250\mu A$                      | $BV_{DSS}$   | 60  | --   | --   | V    |
| Drain-Source On-State Resistance                      | $V_{GS} = 10V, I_D = 30A$                          | $R_{DS(ON)}$ | --  | 5.7  | 6.7  | mΩ   |
| Gate Threshold Voltage                                | $V_{DS} = V_{GS}, I_D = 250\mu A$                  | $V_{GS(TH)}$ | 2   | 3    | 4    | V    |
| Zero Gate Voltage Drain Current                       | $V_{DS} = 48V, V_{GS} = 0V$                        | $I_{DSS}$    | --  | --   | 1    | uA   |
| Gate Body Leakage                                     | $V_{GS} = \pm 20V, V_{DS} = 0V$                    | $I_{GSS}$    | --  | --   | ±100 | nA   |
| Dynamic                                               |                                                    |              |     |      |      |      |
| Total Gate Charge                                     | $V_{DS} = 30V, I_D = 30A,$<br>$V_{GS} = 10V$       | $Q_g$        | --  | 81   | --   | nC   |
| Gate-Source Charge                                    |                                                    | $Q_{gs}$     | --  | 23   | --   |      |
| Gate-Drain Charge                                     |                                                    | $Q_{gd}$     | --  | 24   | --   |      |
| Input Capacitance                                     | $V_{DS} = 30V, V_{GS} = 0V,$<br>$f = 1.0MHz$       | $C_{iss}$    | --  | 4382 | --   | pF   |
| Output Capacitance                                    |                                                    | $C_{oss}$    | --  | 668  | --   |      |
| Reverse Transfer Capacitance                          |                                                    | $C_{rss}$    | --  | 339  | --   |      |
| Switching                                             |                                                    |              |     |      |      |      |
| Turn-On Delay Time                                    | $V_{GS} = 10V, V_{DS} = 30V,$<br>$R_G = 3.3\Omega$ | $t_{d(on)}$  | --  | 25   | --   | nS   |
| Turn-On Rise Time                                     |                                                    | $t_r$        | --  | 19   | --   |      |
| Turn-Off Delay Time                                   |                                                    | $t_{d(off)}$ | --  | 85   | --   |      |
| Turn-Off Fall Time                                    |                                                    | $t_f$        | --  | 43   | --   |      |
| Drain-Source Diode Characteristics and Maximum Rating |                                                    |              |     |      |      |      |
| Drain-Source Diode Forward Voltage                    | $V_{GS}=0V, I_S=20A$                               | $V_{SD}$     | -   | 0.8  | 1.3  | V    |
| Reverse Recovery Time                                 | $I_S = 30A, T_J=25^{\circ}C$                       | $t_{fr}$     |     | 36   |      | nS   |
| Reverse Recovery Charge                               | $dI/dt = 100A/us$                                  | $Q_{fr}$     |     | 53   |      | nC   |

**Notes:**

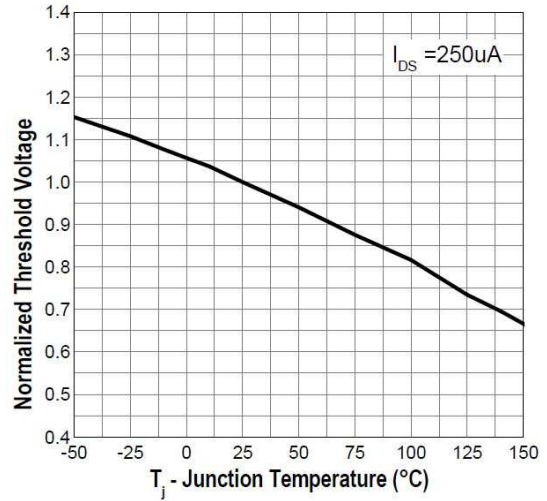
- Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.  $R_{\theta JA}$  shown below for single device operation on FR-4 in still air
- Calculated continuous current based on maximum allowable junction temperature, Package limitation current is 75A

### Electrical Characteristics Curve (Ta = 25°C, unless otherwise noted)

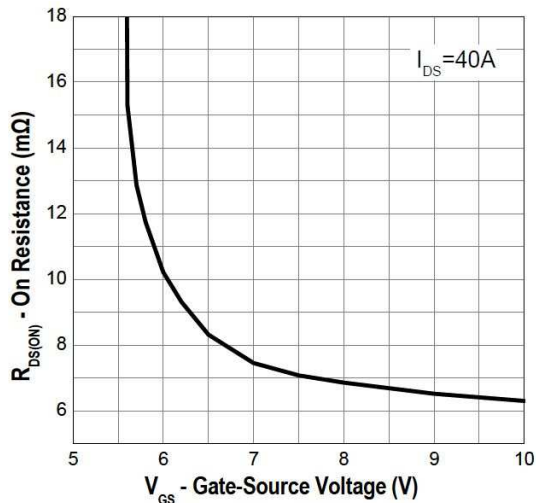
**Output Characteristics**



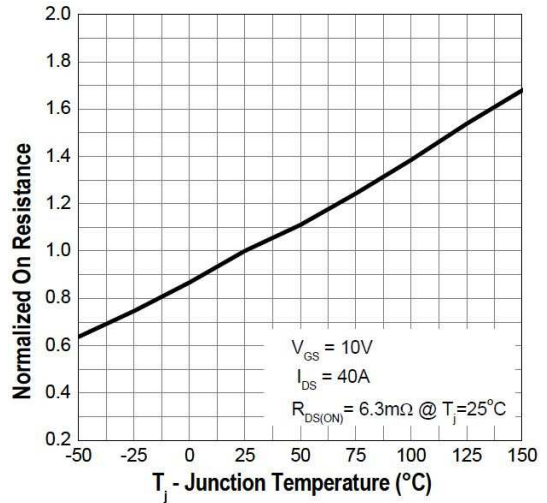
**Gate Threshold Voltage**



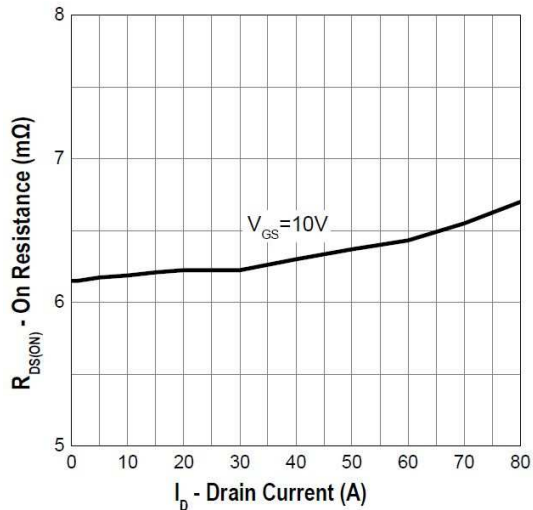
**Gate Source On Resistance**



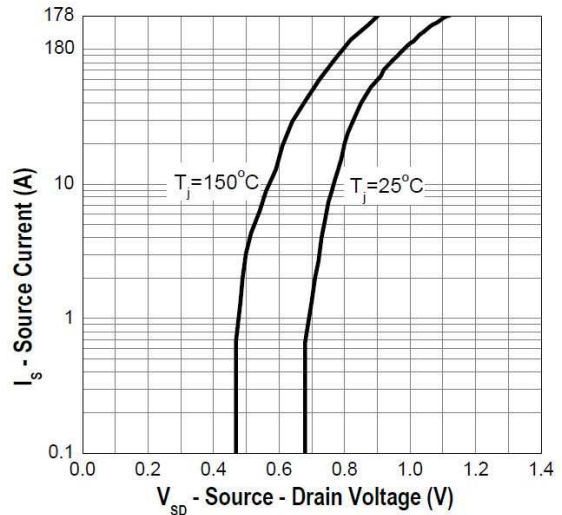
**Drain-Source On Resistance**



**Drain-Source On-Resistance**

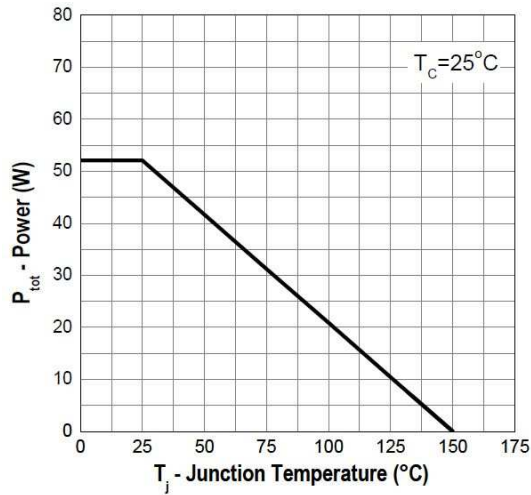


**Source-Drain Diode Forward Voltage**

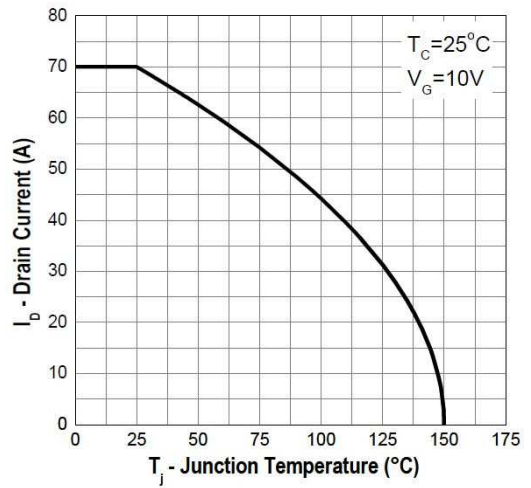


### Electrical Characteristics Curve ( $T_a = 25^\circ\text{C}$ , unless otherwise noted)

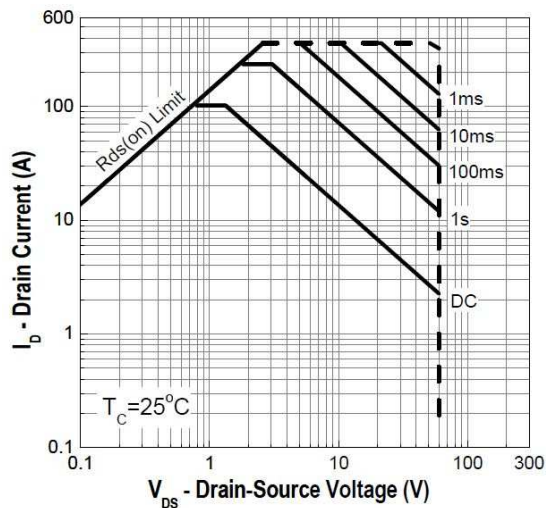
**Power Derating**



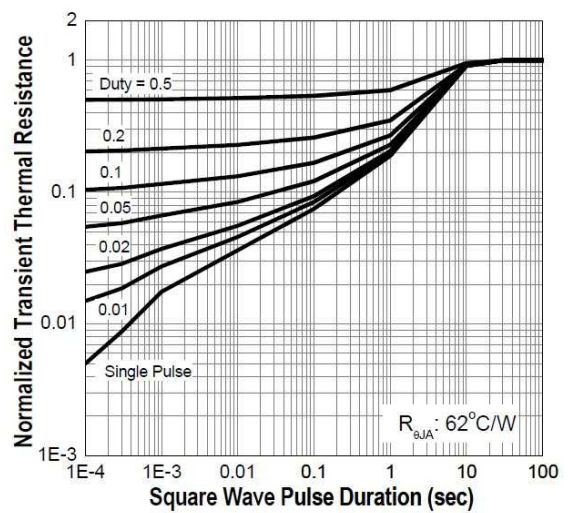
**Drain Current vs. Junction Temperature**



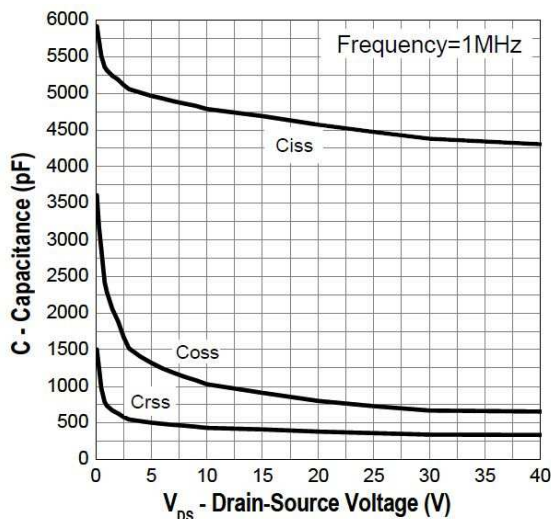
**Safe Operation Area**



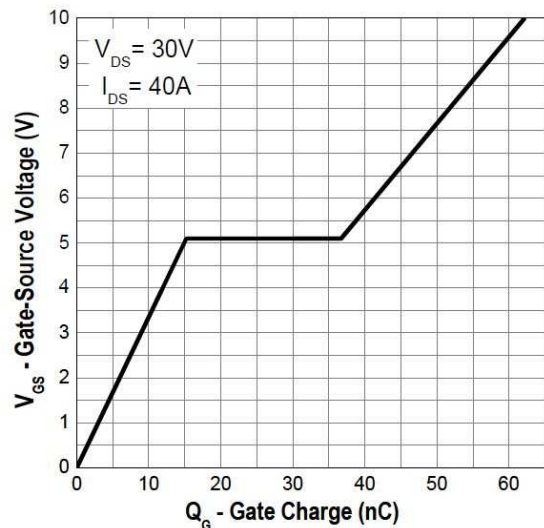
**Transient Thermal Impedance**



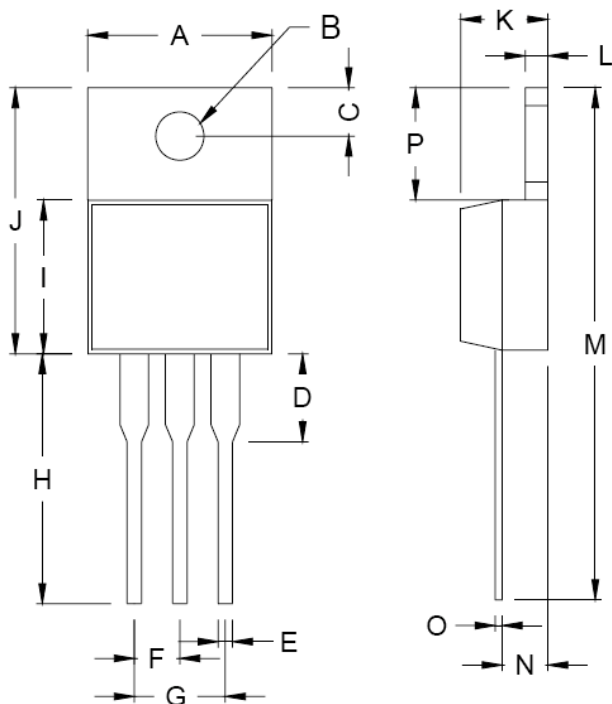
**Capacitance**



**Gate Charge**



**TO-220 Mechanical Drawing**



| TO-220 DIMENSION |             |        |        |       |
|------------------|-------------|--------|--------|-------|
| DIM              | MILLIMETERS |        | INCHES |       |
|                  | MIN         | MAX    | MIN    | MAX   |
| A                | 10.000      | 10.500 | 0.394  | 0.413 |
| B                | 3.740       | 3.910  | 0.147  | 0.154 |
| C                | 2.440       | 2.940  | 0.096  | 0.116 |
| D                | -           | 6.350  | -      | 0.250 |
| E                | 0.381       | 1.106  | 0.015  | 0.040 |
| F                | 2.345       | 2.715  | 0.092  | 0.058 |
| G                | 4.690       | 5.430  | 0.092  | 0.107 |
| H                | 12.700      | 14.732 | 0.500  | 0.581 |
| J                | 14.224      | 16.510 | 0.560  | 0.650 |
| K                | 3.556       | 4.826  | 0.140  | 0.190 |
| L                | 0.508       | 1.397  | 0.020  | 0.055 |
| M                | 27.700      | 29.620 | 1.060  | 1.230 |
| N                | 2.032       | 2.921  | 0.080  | 0.115 |
| O                | 0.255       | 0.610  | 0.010  | 0.024 |
| P                | 5.842       | 6.858  | 0.230  | 0.270 |

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